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WHAT IS CLAIMED IS:

1. A device mounting method comprising:

a device separating step of separating a plurality of devices, which have been arrayed with a specific period on a wafer, into individual devices while keeping the arrayed state of the devices as it is;

a device re-arraying step of handling the individually separated devices so as to re-array the devices at intervals of a value equivalent to the period multiplied by a specific magnification; and

a device transferring step of transferring the re-arrayed devices on a mounting board while keeping the re-arrayed state of the devices as it is.

2. A device mounting method according to claim 1, wherein said device re-arraying step comprises a discrete selection procedure of discretely selecting the devices at intervals of a value equivalent to the period multiplied by an integer magnification;

said device transferring step comprises a partial transfer procedure of transferring the selected devices on a portion of the mounting board; and

the plurality of devices are transferred on the entire surface of the mounting board by repeating said discrete selection procedure and said partial transfer

procedure.

3. A device mounting method according to claim 2, wherein said discrete selection procedure is carried out by peeling only devices, which are selected from the plurality of devices having been separated from each other on the surface of the wafer with the arrayed state thereof kept as it is, from the wafer by irradiating the selected devices with an energy beam emitted from the back surface of the wafer, and temporarily transferring the peeled devices on a temporary board, thereby re-arraying the peeled devices thereon; and

said partial transfer procedure is carried out by finally transferring the devices temporarily transferred on the temporary board on the mounting board.

4. A device mounting method according to claim 1, wherein said device re-arraying step comprises:

a fixation procedure of fixing the individually separated devices on a support enlargeable at a specific magnification while keeping the arrayed state of the devices as it is; and

an enlargement procedure of enlarging the support at the specific magnification, thereby re-arraying the devices with intervals of a value equivalent to the period multiplied by the specific magnification.

5. A device mounting method according to claim 4, wherein said fixation procedure is carried out by fixing the individually separated devices on a film-like support deformable at said specific magnification; and

said enlargement procedure is carried out by drawing the film-like support at said specific magnification.

6. A device mounting method according to claim 4, wherein said fixation procedure is carried out by fixing the individually separated devices on a support previously, repeatedly folded so as to be developable at said specific magnification; and

said enlargement procedure is carried out by developing the support at said specific magnification.

7. A device mounting method according to claim 1, wherein said device separation step is carried out by separating a plurality of devices in such a manner that the devices are two-dimensionally arrayed with a specific period in the longitudinal and lateral directions; and

said device re-arraying step is carried out by one-dimensionally re-arraying the devices in one of the longitudinal and lateral direction, and then one-dimensionally re-arraying the devices in the other of the longitudinal and lateral directions.

8. A device mounting method according to claim 1, wherein said device re-arraying step is carried out by performing a first re-array operation at a first magnification and then performing a second re-array operation at a second magnification, the product of the first magnification and the second magnification being equal to said specific magnification.

9. A device mounting method according to claim 1, wherein said device separating step is carried out by integratedly forming light emitting devices on a semiconductor wafer and separating the integrated light emitting devices into individual light emitting devices; and

said device transferring step is carried out by transferring said light emitting devices at specific intervals on a mounting board of an image display.

10. A device mounting method comprising:

a transfer step of transferring a plurality of devices, which have been arrayed on a wafer, on a mounting board;

wherein the devices are discretely mounted on the mounting board in such a manner as to be re-arrayed with scaled-up intervals.